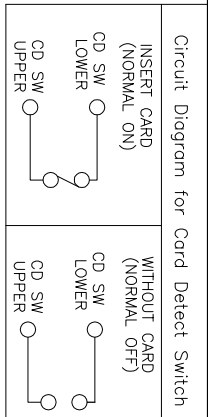
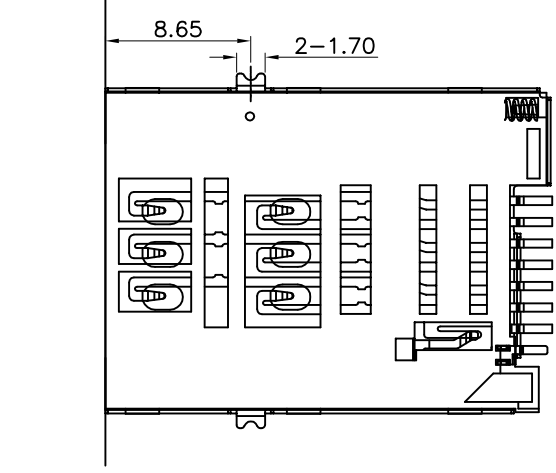
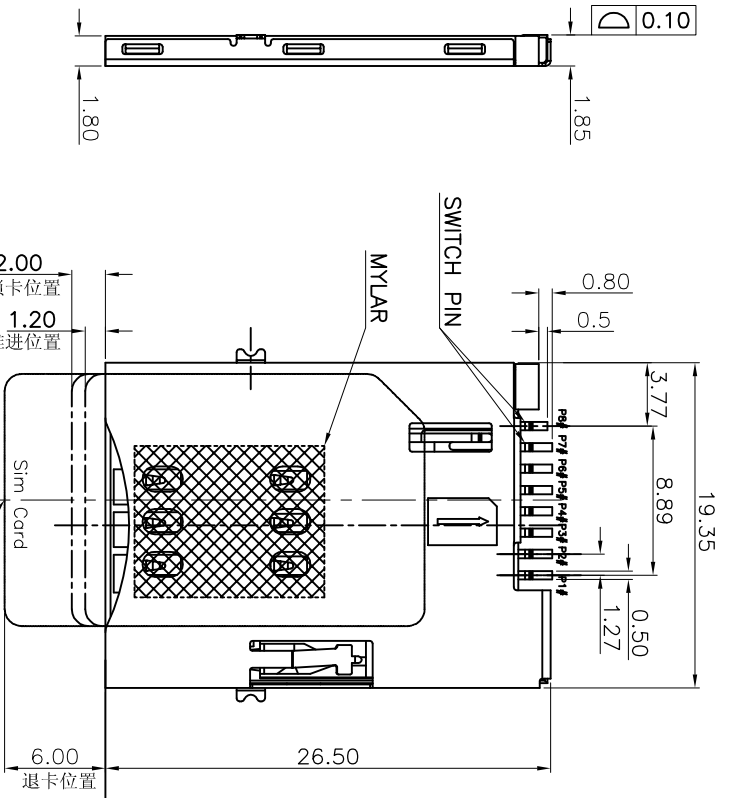
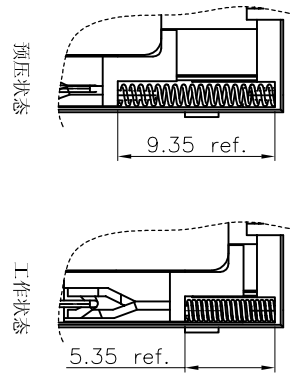
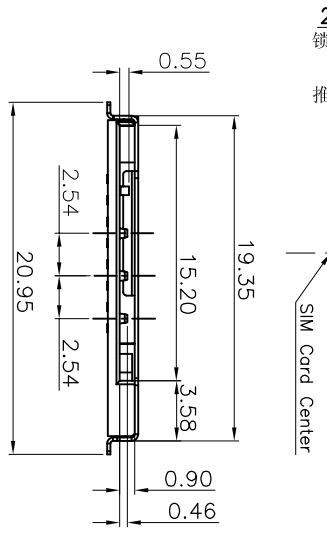
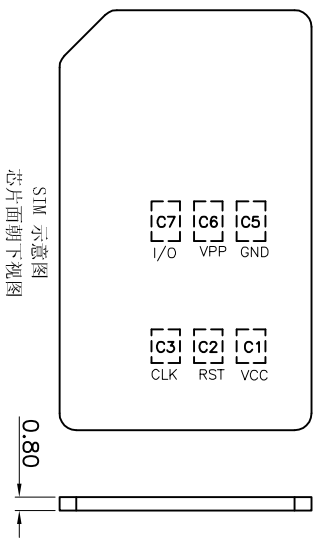


PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:1/O
P7#	POL
P8#	DET



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

- SOLDER AREA
- NONE CIRCUIT DIAGRAM AREA

NOTES:
1)MATERIAL:
HOUSING: LCP UL 94V-0
CONTACT: C5210R-H,T=0.15
SHELL: SUS201,T=0.20
MYLAR: POLYESTER
2)FINISH:
CONTACT:GOLD PLATED ON CONTACT AREA;
GOLD FLASH PLATING ON SOLDER TAILS, WITH
ENTIRE CONTACT UNDERPLATED 50u"Min. NICKEL
SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL,
GOLD FLASH PLATED ON SOLDER TAILS
3.INFRARED REFLOW SOLDERING: 10sec. Min. dt 260±10

GENERAL TOLERANCE	图号	设计	比例
X.±0.25	JYSA1511-001	审核	1:1
X.±0.20	PUSH SIM CARD 6+2PIN 1.85H 无柱(加贴MYLAR)	核准	mm
XX±0.15	.XX±1'	日期	
.XX±0.08	JYS-SIM185-125	2015/10/30	
SHEET 1/1			

JYS 杰宇森电子有限公司
JIE YU SEN ELECTRONIC CO., LTD.

REV.	ECN.NO.	MODIFY CONTENT	DATE
A		NEW	2015/10/30